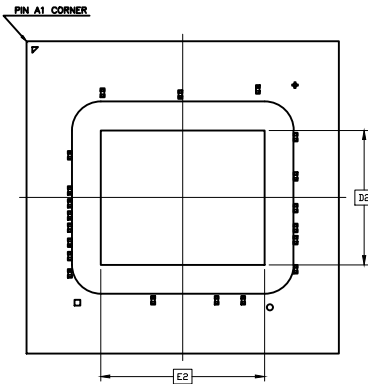
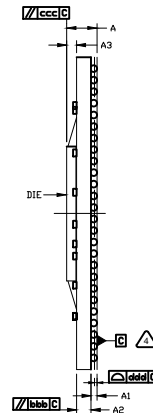


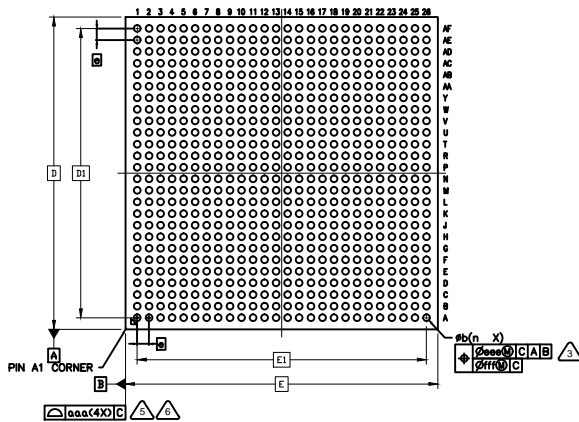
TOP VIEW



SIDE VIEW



	SYMBOL	COMMON DIMENSIONS		
		MIN.	NOM.	MAX.
TOTAL THICKNESS	A	2.423	2.605	2.787
STAND OFF	A1	0.400	0.500	0.600
SUBSTRATE THICKNESS	A2	1.258	REF	
THICKNESS FROM SUBSTRATE SURFACE TO THE HIGHEST POINT	A3	0.847	REF	
BODY SIZE	E	27.000	BSC	
	D	27.000	BSC	
BALL DIAMETER		0.600		
BALL WIDTH	b	0.500	0.600	0.700
BALL PITCH	e	1.000	BSC	
BALL COUNT	n	676		
EDGE BALL CENTER TO CENTER	E1	25.000	BSC	
	D1	25.000	BSC	
EXPOSE DIE SIZE	E2	14.157	BSC	
	D2	11.618	BSC	
PACKAGE EDGE TOLERANCE	aaa	0.200		
SUBSTRATE PARALLELISM	bbb	0.250		
TOP PARALLELISM	ccc	0.200		
COPLANARITY	ddd	0.200		
BALL OFFSET (PACKAGE)	eee	0.250		
BALL OFFSET (BALL)	fff	0.100		



BOTTOM VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]
- PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- JEDEC REFERENCE: JEP95 DR4.14

Title: Package Outline Drawing

Product Family: LAV-AT

Product Name: LAV-AT-70-LFG676

Pkg Type: FCBGA

Pkg I/O Count: 676

Pkg Size: 27x27 mm

Document No:

POD-230013

Rev: C

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